



MIPI Alliance

SLIMbus™ Specification Member Testimonials

Akustica

"Akustica is dedicated to improving voice quality in mobile terminals by providing better microphones that can be used together with algorithms to reduce background noise and allow the user's voice to be clearly heard," said Davin Yuknis, vice president of marketing at Akustica. "The adoption of a standardized audio interface will make the implementation of a high performance voice input solution more straightforward and cost-effective for handset manufacturers - accelerating the time in which end-users will benefit from enhanced sound quality."

Arasan Chip Systems

"We strongly endorse the efforts of the MIPI Alliance in defining and promoting the new SLIMbus Standard. SLIMbus is an important unifying piece for managing the varied low-speed control and data transfer needs of mobile multimedia products. As a Contributor Member in the MIPI Alliance, we have developed the Industry's First SLIMbus IP Core and look forward to helping companies integrate SLIMbus and other MIPI IP Core technology into their products." (Richard Timpa, Vice President Sales, Arasan Chip Systems)

Atmel Corporation

"Atmel is pleased to see the emergence of the SLIMbus standard which is ideally in line with our strategy to provide high performance, low cost solutions built around microcontrollers coupled with analog companion ICs." (Christian Dupuy, Director, Power Management and Analog Companion Products, Atmel Corporation)

austriamicrosystems AG

"As a vendor of integrated power management and audio devices we rely on the advantages of SLIMbus, which offers an ideal 2-wire bus connection at a strongly reduced pin count compared to today's bus solutions." (Mario Manninger, Director Engineering, austriamicrosystems AG)

Broadcom

"Broadcom applauds the finalization of MIPI SLIMbus specification. Our aggressive silicon integration in 65 nanometer and beyond will benefit significantly from small silicon package and low interface pin counts. SLIMbus will help Broadcom deliver lower cost, lower power and smaller form-factor solutions to our customers," said Michael Civiello, Senior Director of Marketing for Broadcom's Mobile Platform Group. "We foresee broad industry adoption for SLIMbus that will help shorten design cycles while enhancing system reliability. As a MIPI Contributor Member and a leading mobile and wireless technology provider, Broadcom intends to support SLIMbus and offer it in future generation devices, as well as to contribute to the global success of MIPI Alliance."

Freescale Semiconductor

"As an active MIPI Alliance Contributor Member, Freescale is a strong supporter of the Alliance's commitment to solving interconnect challenges in mobile wireless and multimedia products," said Kaivan Karimi, Director of Global Strategy for Freescale's Wireless and Mobile Systems Group. "The SLIMbus standard interface further enhances Freescale's portfolio of battery-efficient MXC cellular and i.MX handheld multimedia device platforms by dramatically reducing the traditional complexity of digital audio and control interconnects. This, in turn, helps to reduce our customer's design complexities and improve their time to market."

Infineon

"Infineon considers the MIPI Alliance as an excellent forum to establish open standards and specifications. Open standards will undoubtedly speed up development and time to market for mobile multimedia devices". Said Davoud Samani, VP, Technology Alliances at Infineon Technologies' Communication Solutions business group. "By using the open standards for application interfaces, handset makers can use interoperable building blocks faster and at much lower cost."

LnK

"LnK congratulates all the members of the LML working group for the outstanding effort produced during these last 2 years. LnK is fully committed to support the introduction of the SLIMbus interface in the processors and peripherals by providing the market with a SLIMbus protocol analyzer and SLIMbus test tools. We really hope that this very powerful dedicated tool set will ease the adoption and the system integration of SLIMbus in mobile phones and portable multimedia devices." (Xavier Lambrecht, CEO, LnK)

Motorola

"Motorola is pleased to see the MIPI Alliance reach another important milestone with the release of SLIMbus," said Frans Hoekstra, Director, Future Wireless Modems and Technologies, Motorola. "As a MIPI board member and active participant in the development of SLIMbus, Motorola sees great potential for the use of this interface."

National Semiconductor

"The SLIMbus specification simplifies mobile phone system design by unifying digital audio content and control data into one bus structure. It supports high performance and reduces complexity, size and pin-count. National Semiconductor expects to implement SLIMbus on selected audio ICs moving forward." (Kenneth Boyce, Technology Director, National Semiconductor Audio Products Group)

Nokia

"Nokia as one of the founders of MIPI is pleased to see SLIMbus specifications to have been completed. SLIMbus builds on the foundation of several previously used peripheral interfaces unifying their functionality into a single interface which increases interoperability and simplifies both hardware and software implementation in mobile devices. It enables, for example, wide expansion of audio features, sensors, and other user interface devices." (Petri Haavisto, VP Architecture & System Design, Nokia)

NXP Semiconductors

"NXP has been participating in SLIMbus development from the beginning of 2004. We firmly believe that SLIMbus will bring the next step in simplifying existing phone architectures while enabling new use cases. Because of these advantages, we are convinced that SLIMbus will be rapidly adopted by the mobile industry. NXP will implement SLIMbus in baseband, multimedia processor and peripheral ICs". (Rene Penning de Vries, SVP and Chief Technology Officer NXP Semiconductors)

Samsung Electronics

"Samsung welcomes the advanced digital audio capabilities and compact handset design enabled by the new MIPI SLIMbus standard. We look forward to bringing these benefits to the customers of our semiconductor products, and to all consumers fascinated by the best mobile music experience," said Yiwon Wong, vice president, marketing team, System LSI Division, Semiconductor Business, Samsung Electronics. "We look forward to broad adoption of the new SLIMbus standard across the mobile industry!"

Sonion

Having followed and actively participated in the development of SLIMbus(TM) since the beginning, Sonion is pleased to see the outcome; a specification that will lead to improved handset architecture of unprecedented simplicity and efficiency.

"SLIMbus(TM) is to handset architecture what bridges are to highways. We will support this standard and do everything in our power to aid its adoption, and make it go as fast as possible", said Peter U. Scheel, President & CEO of Sonion.

The anticipation is that the whole handset market will benefit from the SLIMbus(TM) audio bus and that Sonion, as a leading acoustic component manufacturer, will increase functionality and performance of its products noticeably.

STMicroelectronics

"STMicroelectronics a founding member of MIPI welcomes the addition of Slimbus to the MIPI specification portfolio" said Tommi Uhari Executive Vice President of Mobile Multimedia and Communication Group. "MIPI is a worldwide mobile industry supported Alliance, consolidating his contribution and added value to the mobile industry with this new open specification. STMicroelectronics will implement Slimbus in its mobile products offer."

Texas Instruments

"Following the rapidly evolving multimedia capability of mobile devices, our customers need an optimized audio & control interface to give them greater flexibility in designing their systems", said Avner Goren, Director of Strategic Marketing for TI's Wireless Terminals Business Unit. "The SLIMbus standard is ideally suited to deliver the functionality these systems require, while minimizing interface signals and power consumption. As a MIPI Alliance Board Member and an active participant in the development of the SLIMbus standard, TI plans to implement SLIMbus in future TI products and looks forward to the benefits it will provide the industry."

Wolfson Microelectronics

"SLIMbus fits very well with Wolfson's mixed-signal integration approach to system architecture. It satisfies increasingly sophisticated end-user demands by enabling more compact mobile phones, with increased functionality, higher performance audio, and extended battery life. The combination of device control and media streaming in one multi-drop bus comprising only two wires is very powerful, enabling lower power and smaller board area.

We are expecting SLIMbus to find its feet pretty quickly and soon receive widespread acceptance across a wide spectrum of mobile optimised platforms." (Peter Frith, CTO, Wolfson)

XMOS Semiconductor

"We at XMOS are developing low cost software defined silicon devices for the consumer mobile market. We are focusing our efforts on the new MIPI SLIMbus interface and looking to help system developers to differentiate and create new and exciting products." Says James Foster, CEO, XMOS Semiconductor.